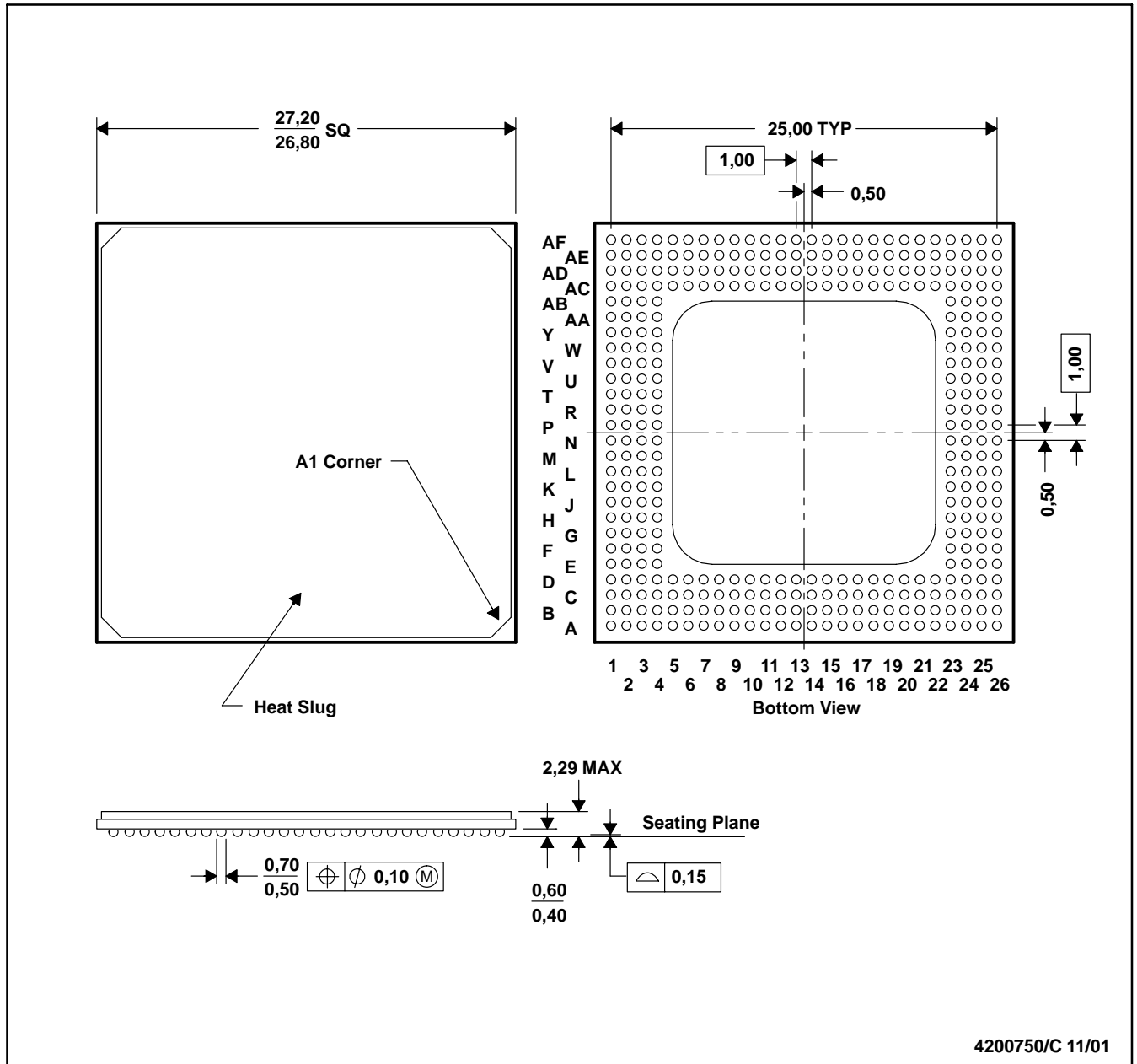


GKN (S-PBGA-N352)

PLASTIC BALL GRID ARRAY (CAVITY DOWN)



4200750/C 11/01

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Thermally enhanced plastic package with heat slug (HSL)

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### Mailing Address:

Texas Instruments  
Post Office Box 655303  
Dallas, Texas 75265